

3W Warm White High Power LED  
Technical Data Sheet

Part No.: LL-HP70MW6F

## Features:

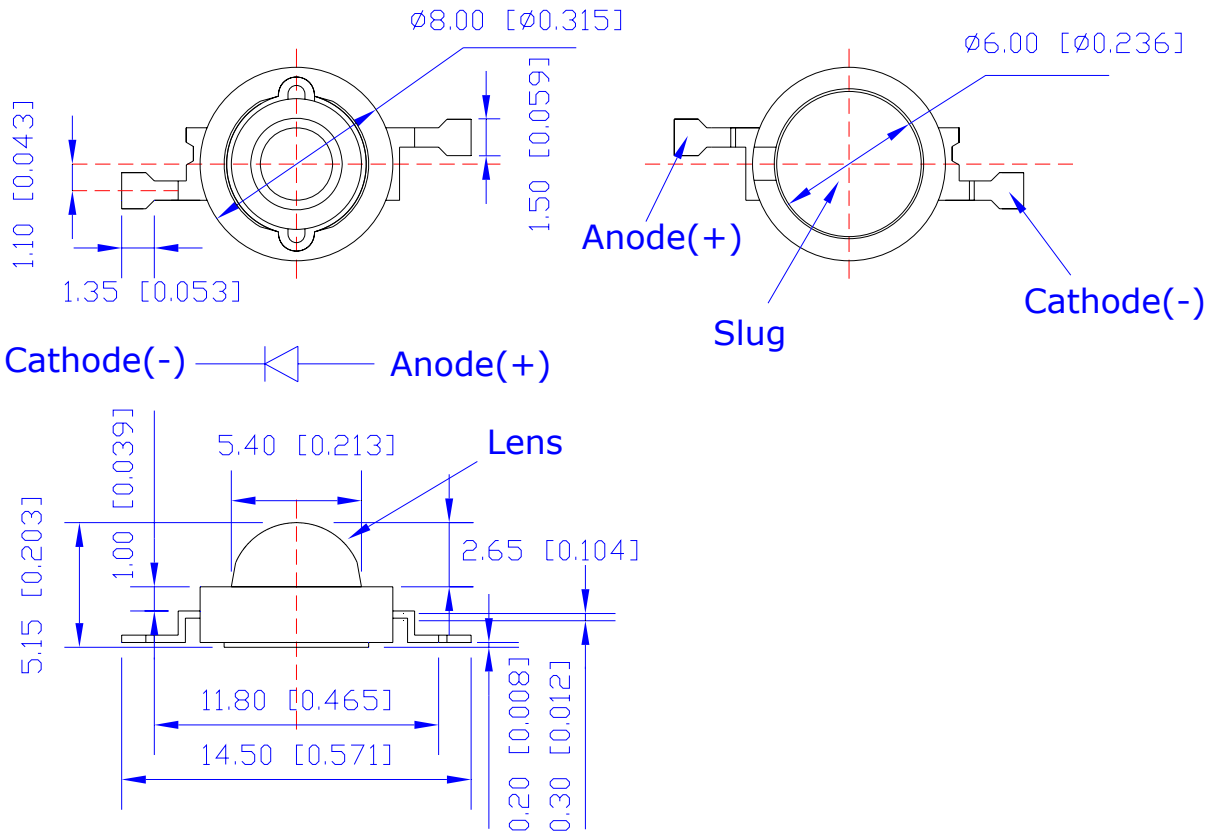
- ◇ Small package with high efficiency
- ◇ Long operating life.
- ◇ Available in white, green, blue, red, yellow.
- ◇ Typical color temperature: 3000 K.
- ◇ View angle: 135°.
- ◇ Low voltage DC operated.
- ◇ The product itself will remain within RoHS compliant Version.



## Applications:

- ◇ Reading lights (car, bus, aircraft).
- ◇ Portable (flashlight, bicycle).
- ◇ Mini\_accent/Uplighters/Downlighters/Orientation.
- ◇ Bollards/Security/Garden.
- ◇ Cove/Undershelf/Task.
- ◇ Automotive rear combination lamps.
- ◇ Traffic signaling/Beacons/ Rail crossing and Wayside.
- ◇ Indoor/Outdoor Commercial and Residential Architectural.
- ◇ Edge\_lit signs (Exit, point of sale).
- ◇ LCD Backlights/Light Guides.

### Mechanical Dimensions:



Part No.	Chip Material	Source Color
LL-HP70MW6F	InGaN	Warm White

#### Notes:

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.25$  mm (.010") unless otherwise noted.

### Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Rating	Units
Forward Current	<b>IF</b>	700	mA
PeakPulseCurrent (tp≤100μs, Duty cycle=0.25)	<b>I pulse</b>	1000	mA
Reverse Voltage	<b>VR</b>	5	V
LED Junction Temperature	<b>Tj</b>	125	°C
Operating Temperature Range	<b>Topr</b>	-40 to +80	°C
Storage Temperature Range	<b>Tstg</b>	-40 to +100	°C
Soldering Time at 260 °C (Max.)	<b>Tsol</b>	5	Seconds

#### Notes:

1. Proper current derating must be observed to maintain junction temperature below the maximum.
2. LEDs are not designed to be driven in reserve bias.

### Electrical Optical Characteristics at Ta=25°C

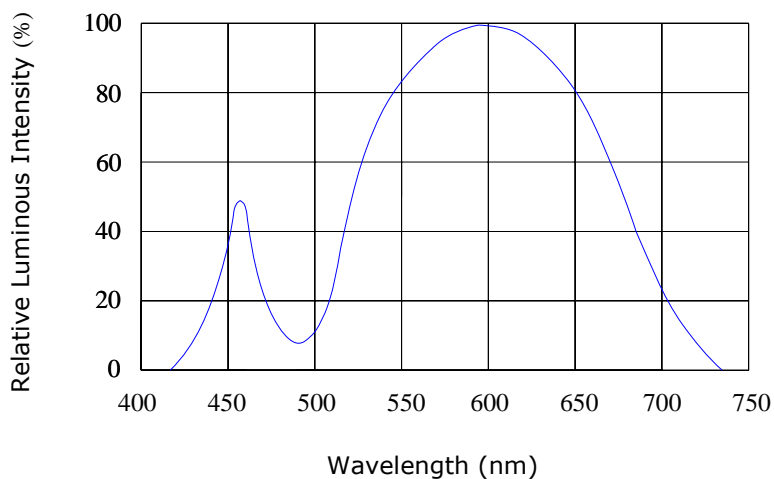
Parameters	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Viewing Angle [1]	<b>2θ<sub>1/2</sub></b>	---	135	--	Deg	IF=700mA
Forward Voltage [2]	<b>V<sub>F</sub></b>	2.8	3.5	4.0	V	IF=700mA
Reverse Current	<b>I<sub>R</sub></b>	---	---	10	μA	V <sub>R</sub> =5V
Color Temperature [3]	<b>CCT</b>	2600	3000	4000	k	IF=700mA
Luminous Flux	<b>Φ<sub>v</sub></b>	130	150	---	lm	IF=700mA

#### Notes:

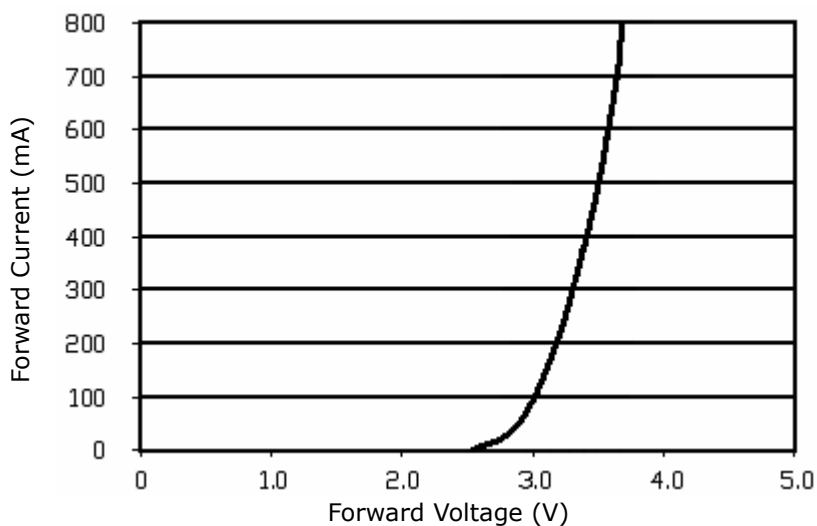
1. 2θ<sub>1/2</sub> is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
2. Forward Voltage measurement tolerance : ±0.1V
3. X, Ycoordination for white light bin areas refer to EHP-A08 series White and Warm White Binning (DSE-A08-001).

**Typical Electrical-Optical Characteristics Curves  
(25°C Ambient Temperature Unless Otherwise Noted)**

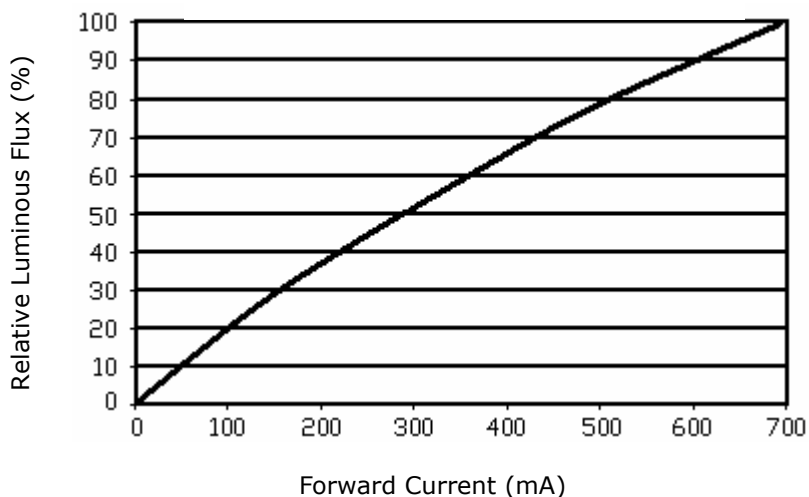
**Relative Spectral Distribution**



**Forward Current VS Forward Voltage**

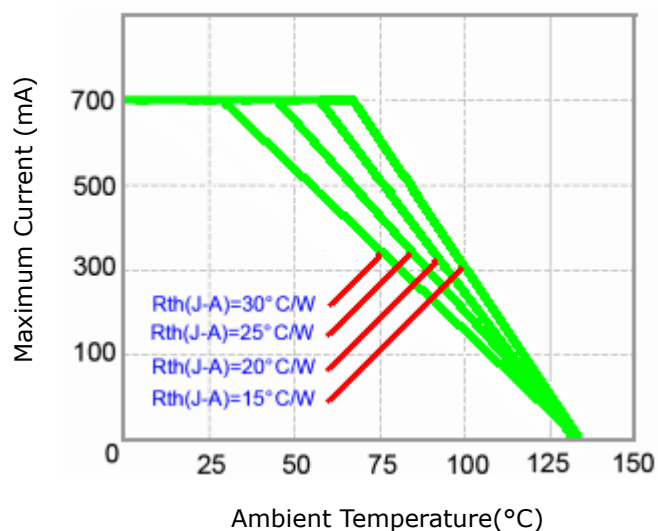


**Luminous Flux VS Forward**

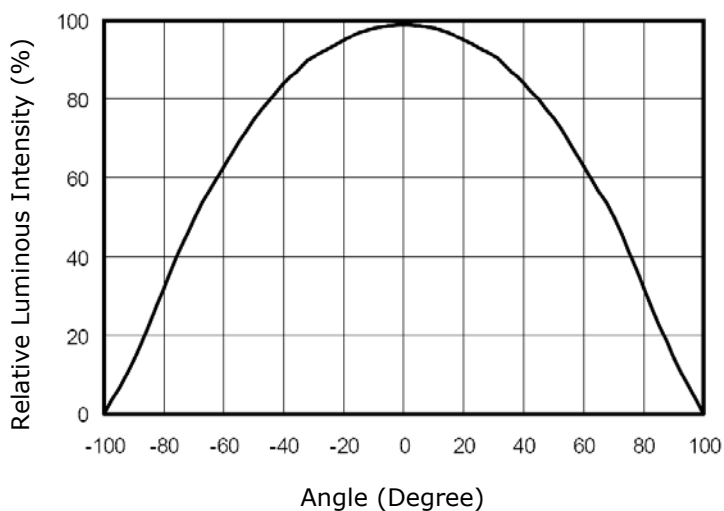


### Typical Electrical-Optical Characteristics Curves

Maximum Current (mA) VS Ambient



Typical Spatial Radiation Pattern



## Precautions For Use:

### 1. Over-current-proof

Though HP70M has conducted ESD protection mechanism, customer must not use the device in reverse and should apply resistors for extra protection. Otherwise slight voltage shift may cause enormous current change and burn out failure would happen.

### 2. Storage

- ① Do not open moisture proof bag before the products are ready to use.
- ② Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- ③ The LEDs should be used within a year.
- ④ After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.
- ⑤ The LEDs should be used within 168 hours (7 days) after opening the package.
- ⑥ If the moisture absorbent material (silicone gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
- ⑦ Pre-curing treatment: 60±5°C for 24 hours.

### 3. Thermal Management

- ① Because HP70M LED is a high power dissipation device, special and sufficient consideration in thermal management design must be made to optimize the thermal performance.
- ② Heat sink design is implemented in the device for an additional thermal connection. Since the device is capable of SMT process, tin must be spread both heat sink and solder pads areas to dissipate the heat.
- ③ A high thermal conductivity substrate, such as Aluminum or Copper plate etc, must be applied for external thermal management. It is strongly recommended that the outer heat sink or PCB dimension per LED can not be less than 25 x 25 x 1 (L x W x H) mm. The materials for outer heat sink can be FR4 on Aluminum, MCPCB, or FPC on Aluminum.
- ④ Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.
- ⑤ Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and LED lifetime will decrease critically.

### 4. Soldering Condition

- ① Soldering should not be done more than two times.
- ② While soldering, do not put stress on the LEDs during heating.
- ③ After soldering, do not warp the circuit board.

## 5. Soldering Iron

- ① For prototype builds or small series production runs it is possible to place and solder the LED by hand.
- ② It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.
- ③ Be careful because the damage of the product is often started at the time of the hand solder.

## 6. Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible.

Sharp objects of all types should not be used to pierce the sealing compound.